- **Single- or Dual-Supply Operation**
- **Wide Range of Supply Voltages**
  1.5 V to 18 V
- **Very Low Supply Current Drain**
  150 µA Typ at 5 V
  65 µA Typ at 1.4 V
- **Built-In ESD Protection**
- **High Input Impedance . . . 10^{12} Ω Typ**
- **Extremely Low Input Bias Current 5 pA Typ**
- **Ultrastable Low Input Offset Voltage**
- **Input Offset Voltage Change at Worst-Case Input Conditions Typically 0.23 µV/ Month, Including the First 30 Days**
- **Common-Mode Input Voltage Range Includes Ground**
- **Outputs Compatible With TTL, MOS, and CMOS**
- **Pin-Compatible With LM393**

TLC352C, TLC352I . . . D OR P PACKAGE
(TOP VIEW)

1OUT	1	8	V_{DD}
1IN–	2	7	2OUT
1IN+	3	6	2IN–
GND	4	5	2IN+
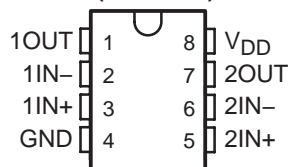
symbol (each comparator)
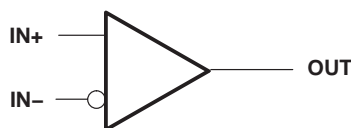
description

This device is fabricated using LinCMOS™ technology and consists of two independent voltage comparators, each designed to operate from a single power supply. Operation from dual supplies is also possible if the difference between the two supplies is 1.4 V to 18 V. Each device features extremely high input impedance (typically greater than 10^{12} Ω), which allows direct interface to high-impedance sources. The output are n-channel open-drain configurations and can be connected to achieve positive-logic wired-AND relationships. The capability of the TLC352 to operate from 1.4-V supply makes this device ideal for low-voltage battery applications.

The TLC352 has internal electrostatic discharge (ESD) protection circuits and has been classified with a 2000-V ESD rating tested under MIL-STD-883C, Method 3015. However, care should be exercised in handling this device as exposure to ESD may result in degradation of the device parametric performance.

The TLC352C is characterized for operation from 0°C to 70°C. The TLC352I is characterized for operation over the industrial temperature range of – 40°C to 85°C.

AVAILABLE OPTIONS

T_A	V_{IO} max AT 25°C	PACKAGE	
		SMALL-OUTLINE (D)	PLASTIC DIP (P)
0°C to 70°C	5 mV	TLC352CD	TLC352CP
– 40°C to 85°C	5 mV	TLC352ID	TLC352IP

The D packages are available taped and reeled. Add R suffix to device type (e.g., TLC352 CDR).

LinCMOS is a trademark of Texas Instruments Incorporated.

Copyright © 2002, Texas Instruments Incorporated

TEXAS INSTRUMENTS

TLC352
LinCMOS™ DUAL DIFFERENTIAL COMPARATOR

equivalent schematic (each comparator)
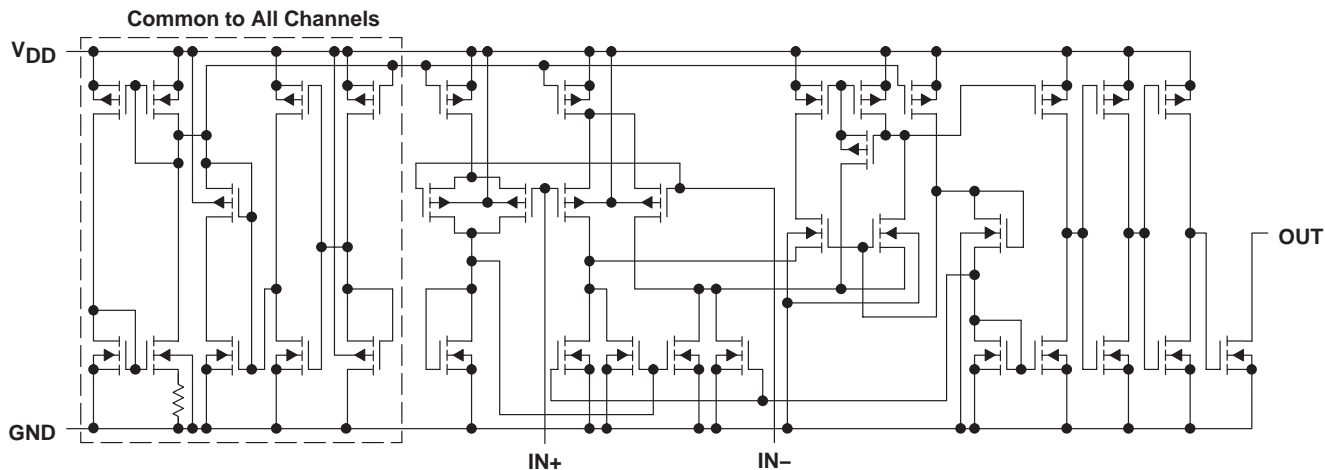
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD} (see Note 1) . . . . 18 V

Differential input voltage, V_{ID} (see Note 2) . . . . ± 18 V

Input voltage, V_I . . . . V_{DD}

Input voltage range, V_I . . . . – 0.3 V to 18 V

Output voltage, V_O . . . . 18 V

Input current, I_I . . . . ± 5 mA

Output current, I_O . . . . 20 mA

Duration of output short circuit to ground (see Note 3) . . . . unlimited

Continuous total dissipation . . . . See Dissipation Rating Table

Operating free-air temperature range, T_A TLC352C . . . . 0°C to 70°C

TLC352I . . . . – 40°C to 85°C

Storage temperature range . . . . – 65°C to 150°C

Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or P package . . . . 260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and
functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not
implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values except differential voltages are with respect to the network ground.
2. Differential voltages are at IN+ with respect to IN –.
3. Short circuits from outputs to V_{DD} can cause excessive heating and eventual device destruction.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR	DERATE ABOVE T_A	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING
D	500 mW	5.8 mW/°C	64°C	464 mW	377 mW
P	500 mW	N/A	N/A	500 mW	500 mW

recommended operating conditions

		TLC352C		TLC352I		UNIT
		MIN	MAX	MIN	MAX	
Supply voltage, V$_{DD}$		1.4	16	1.4	16	V
Common-mode input voltage, V$_{IC}$	V$_{DD}$ = 5 V	0	3.5	0	3.5	V
	V$_{DD}$ = 10 V	0	8.5	0	8.5	
Operating free-air temperature, T$_A$		0	70	– 40	85	°C

electrical characteristics at specified free-air temperature, V$_{DD}$ = 1.4 V (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	T$_A$†	TLC352C			TLC352I			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V$_{IO}$	Input offset voltage	V$_{IC}$ = V$_{ICR}$ min, See Note 4	25°C		2	5		2	5	mV
			Full range			6.5			7	
I$_{IO}$	Input offset current		25°C		1			1		pA
			MAX			0.3			1	nA
I$_{IB}$	Input bias current		25°C		5			5		pA
			MAX			0.6			2	nA
V$_{ICR}$	Common-mode input voltage range		Full range	0 to 0.2			0 to 0.2			V
V$_{OL}$	Low-level output voltage		25°C		100	200		100	200	mV
			Full range			200			200	
I$_{OL}$	Low-level output current	V$_{ID}$ = – 0.5 V, V$_{OL}$ = 0.3 V	25°C	1	1.6		1	1.6		mA
I$_{DD}$	Supply current (two comparators)	V$_{ID}$ = 0.5 V, No load	25°C		65	150		65	150	µA
			Full range			200			200	

† All characteristics are measured with zero common-mode input voltage unless otherwise noted. Full range is 0°C to 70°C for TLC352C, – 40°C to 85°C for TLC352I. IMPORTANT: See Parameter Measurement Information.

NOTE 4: The offset voltage limits given are the maximum values required to drive the output above 1.25 V or below 150 mV with a 10-kΩ resistor between the output and V$_{DD}$. They can be verified by applying the limit value to the input and checking for the appropriate output state.

TLC352
LinCMOS™ DUAL DIFFERENTIAL COMPARATOR

SLCS016A – SEPTEMBER 1985 – REVISED SEPTEMBER 2002

electrical characteristics at specified free-air temperature, V_{DD} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A†	TLC352C MIN	TLC352C TYP	TLC352C MAX	TLC352I MIN	TLC352I TYP	TLC352I MAX	UNIT
V_{IO}	Input offset voltage	$V_{IC} = V_{ICR}$ min, See Note 5	25°C		1	5		1	5	mV
			Full range			6.5			7	
I_{IO}	Input offset current		25°C		1			1		pA
			MAX			0.3			1	nA
I_{IB}	Input bias current		25°C		5			5		pA
			MAX			0.6			2	nA
V_{ICR}	Common-mode input voltage range		25°C	0 to $V_{DD}-1$			0 to $V_{DD}-1$			V
			Full range	0 to $V_{DD}-1.5$			0 to $V_{DD}-1.5$			
I_{OH}	High-level output current	$V_{ID} = 1$ V $V_{OH} = 5$ V	25°C		0.1			0.1		nA
		$V_{OH} = 15$ V	Full range			1			1	µA
V_{OL}	Low-level output voltage	$V_{ID} = 1$ V, $I_{OL} = 4$ mA	25°C		150	400		150	400	mV
			Full range			700			700	
I_{OL}	Low-level output current	$V_{ID} = -1$ V, $V_{OL} = 1.5$ V	25°C	6	16		6	16		mA
I_{DD}	Supply current (two comparators)	$V_{ID} = 1$ V, No load	25°C		0.15	0.3		0.15	0.3	mA
			Full range			0.4			0.4	

† All characteristics are measured with zero common-mode input voltage unless otherwise noted. Full range is 0°C to 70°C for TLC352C, – 40°C to 85°C for TLC352I. IMPORTANT: See Parameter Measurement Information.

NOTE 5: The offset voltage limits given are the maximum values required to drive the output above 4 V or below 400 mV with a 10-kΩ resistor between the output and V_{DD}. They can be verified by applying the limit value to the input and checking for the appropriate output state.

switching characteristics, V_{DD} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS		TLC352C, TLC352I MIN	TLC352C, TLC352I TYP	TLC352C, TLC352I MAX	UNIT
Response time	R_L connected to 5 V through 5.1 kΩ, C_L = 15 pF‡, See Note 6	100-mV input step with 5-mV overdrive		650		ns
		TTL-level input step		200		

‡ C_L includes probe and jig capacitance.
NOTE 6: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

TEXAS INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION

The digital output stage of the TLC352 can be damaged if it is held in the linear region of the transfer curve. Conventional operational amplifier/comparator testing incorporates the use of a servo loop that is designed to force the device output to a level within this linear region. Since the servo-loop method of testing cannot be used, the following alternative for measuring parameters such as input offset voltage, common-mode rejection, etc., are offered.

To verify that the input offset voltage falls within the limits specified, the limit value is applied to the input as shown in Figure 1(a). With the noninverting input positive with respect to the inverting input, the output should be high. With the input polarity reversed, the output should be low.

A similar test can be made to verify the input offset voltage at the common-mode extremes. The supply voltages can be slewed as shown in Figure 1(b) for the V_{ICR} test, rather than changing the input voltages, to provide greater accuracy.

A close approximation of the input offset voltage can be obtained by using a binary search method to vary the differential input voltage while monitoring the output state. When the applied input voltage differential is equal but opposite in polarity to the input offset voltage, the output changes state.

(a) V_{IO} WITH $V_{IC} = 0$ (b) V_{IO} WITH $V_{IC} = 4$ V
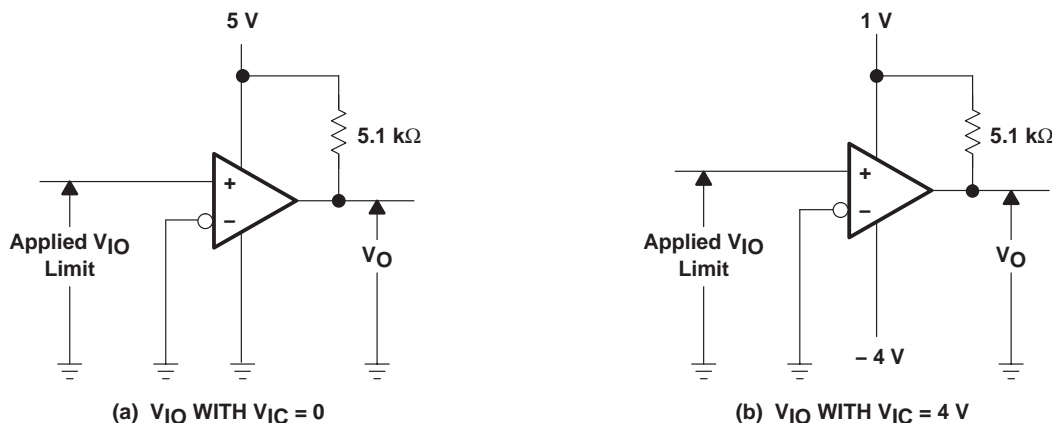
Figure 1. Method for Verifying That Input Offset Voltage Is Within Specified Limits

TLC352
LinCMOS™ DUAL DIFFERENTIAL COMPARATOR

PARAMETER INFORMATION

Figure 2 illustrates a practical circuit for direct dc measurement of input offset voltage that does not bias the comparator into the linear region. The circuit consists of a switching-mode servo loop in which U1a generates a triangular waveform of approximately 20-mV amplitude. U1b acts as a buffer, with C2 and R4 removing any residual dc offset. The signal is then applied to the inverting input of the comparator under test, while the noninverting input is driven by the output of the integrator formed by U1c through the voltage divider formed by R9 and R10. The loop reaches a stable operating point when the output of the comparator under test has a duty cycle of exactly 50%, which can only occur when the incoming triangle wave is sliced symmetrically or when the voltage at the noninverting input exactly equals the input offset voltage.

Voltage divider R9 and R10 provides a step up of the input offset voltage by a factor of 100 to make measurement easier. The values of R5, R8, R9, and R10 can significantly influence the accuracy of the reading; therefore, it is suggested that their tolerance level be 1% or lower.

Measuring the extremely low values of input current requires isolation from all other sources of leakage current and compensation for the leakage of the test socket and board. With a good picoammeter, the socket and board leakage can be measured with no device in the socket. Subsequently, this open-socket leakage value can be subtracted from the measurement obtained with a device in the socket to obtain the actual input current of the device.
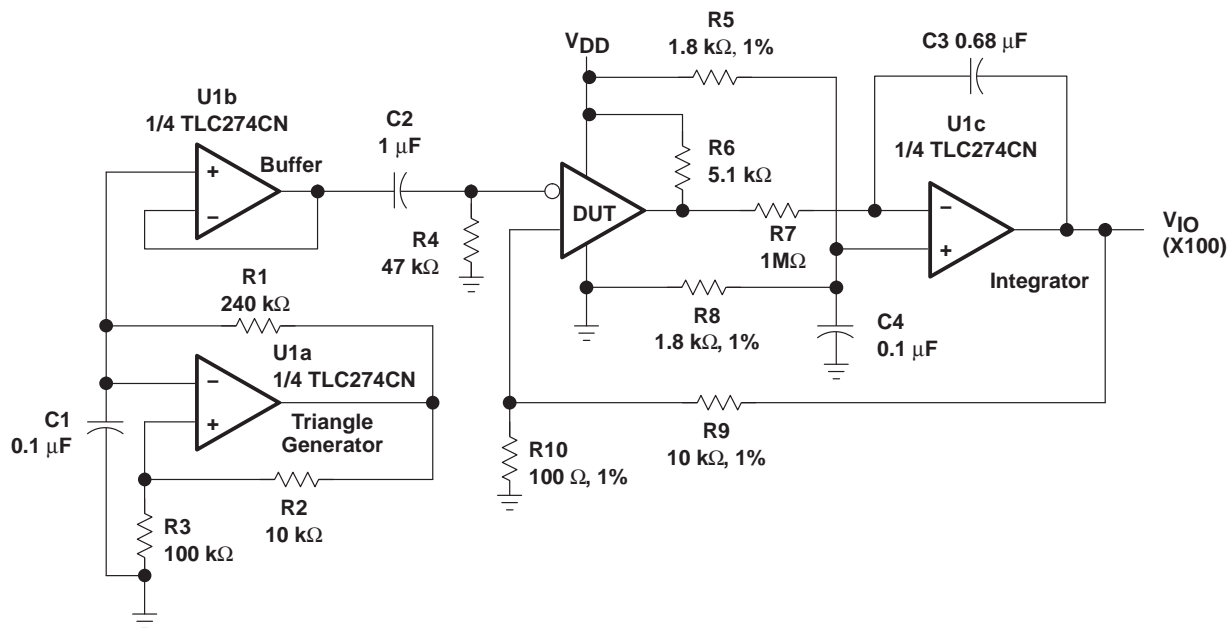

Figure 2. Circuit for Input Offset Voltage Measurement

PARAMETER MEASUREMENT INFORMATION

Response time is defined as the interval between the application of an input step function and the instant when the output reaches 50% of its maximum value. Response time, low-to-high-level output, is measured from the leading edge of the input pulse, while response time, high-to-low level output, is measured from the trailing edge of the input pulse. Response-time measurement at low input signal levels can be greatly affected by the input offset voltage. The offset voltage should be balanced by the adjustment at the inverting input (as shown in Figure 3) so that the circuit is just at the transition point. Then a low signal, for example 105-mV or 5-mV overdrive, causes the output to change state.
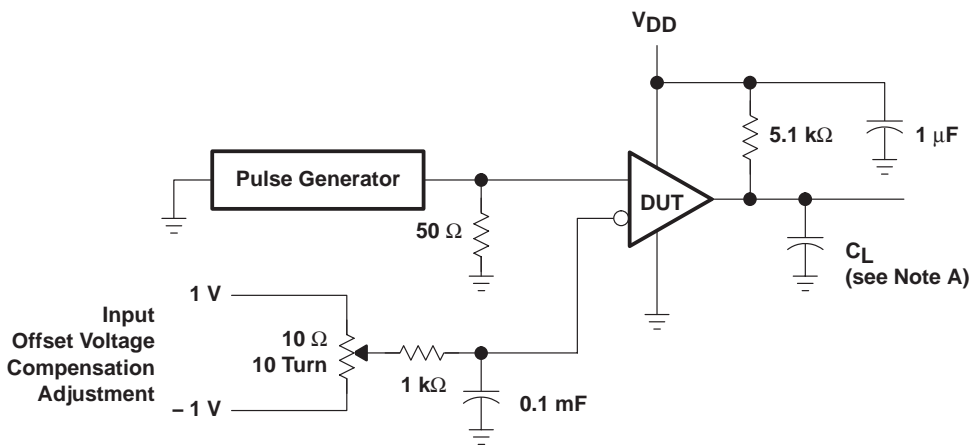
TEST CIRCUIT
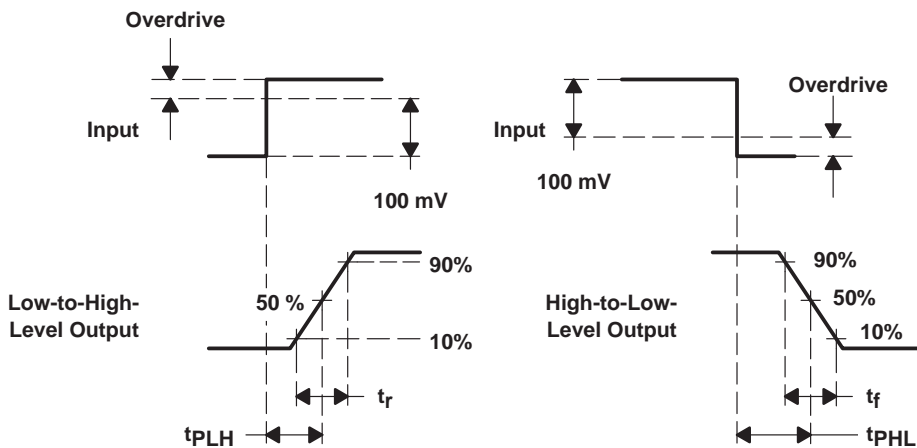
VOLTAGE WAVEFORMS

NOTE A: C_L includes probe and jig capacitance.

Figure 3. Response, Rise, and Fall Times Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC352CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	352C	Samples
TLC352CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	352C	Samples
TLC352CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	352C	Samples
TLC352CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	352C	Samples
TLC352CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TLC352CP	Samples
TLC352CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TLC352CP	Samples
TLC352CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	P352	Samples
TLC352ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	352I	Samples
TLC352IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	352I	Samples
TLC352IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	352I	Samples
TLC352IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	352I	Samples
TLC352IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	TLC352IP	Samples
TLC352IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	P352I	Samples
TLC352IPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	P352I	Samples
TLC352IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	P352I	Samples
TLC352IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	P352I	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

[4] There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

[5] Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

[6] Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC352CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC352CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC352IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC352IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

![Texas Instruments logo] **PACKAGE MATERIALS INFORMATION**

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC352CDR	SOIC	D	8	2500	340.5	338.1	20.6
TLC352CPWR	TSSOP	PW	8	2000	367.0	367.0	35.0
TLC352IDR	SOIC	D	8	2500	340.5	338.1	20.6
TLC352IPWR	TSSOP	PW	8	2000	367.0	367.0	35.0

P (R-PDIP-T8)   PLASTIC DUAL-IN-LINE PACKAGE

0.400 (10,16)
0.355 (9,02)

8   5

0.260 (6,60)
0.240 (6,10)

1   4

0.070 (1,78)
0.045 (1,14)

0.045 (1,14)
0.030 (0,76)

0.020 (0,51) MIN

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

0.200 (5,08) MAX

Gauge Plane

Seating Plane

0.010 (0,25) NOM

0.125 (3,18) MIN

0.100 (2,54)

0.430 (10,92)
MAX

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

4040082/E 04/2010

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   Falls within JEDEC MS-001 variation BA.

6.6 / 6.2 TYP

A

PIN 1 ID
AREA

1

8

6X 0.65

3.1 / 2.9 NOTE 3

2X
1.95

4

5

8X 0.30 / 0.19

⊕ 0.1 Ⓜ C AⓈ BⓈ

B

4.5 / 4.3
NOTE 4

C

SEATING PLANE

⌒ 0.1 C

1.2 MAX

SEE DETAIL A

(0.15) TYP

0.25
GAGE PLANE

0° - 8°

0.75 / 0.50

0.15 / 0.05

DETAIL A
TYPICAL

4221848/A   02/2015

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

8X (0.45)

8X (1.5)

SYMM

(R0.05) TYP

1

8

SYMM

6X (0.65)

4

5

(5.8)

LAND PATTERN EXAMPLE
SCALE:10X

SOLDER MASK OPENING

METAL

0.05 MAX ALL AROUND

NON SOLDER MASK DEFINED

METAL UNDER SOLDER MASK

SOLDER MASK OPENING

0.05 MIN ALL AROUND

SOLDER MASK DEFINED

SOLDER MASK DETAILS
NOT TO SCALE

4221848/A   02/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221848/A   02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

D (R−PDSO−G8)   PLASTIC SMALL OUTLINE

0.197 (5,00)
0.189 (4,80)
△C

8   5

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)   △D

Pin 1
Index Area

1   4

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

Gauge Plane

0.010 (0,25)

0°−8°

⌓ 0.004 (0,10)

Seating Plane

0.050 (1,27)
0.016 (0,40)

4040047−3/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         △C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0.006 (0,15) each side.
         △D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
         E. Reference JEDEC MS−012 variation AA.

TEXAS INSTRUMENTS
www.ti.com

D (R−PDSO−G8)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

←— 6x1,27

5,40

Stencil Openings
(Note D)

←—8x0,55

8x1,50

←—6x1,27

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

—0,60

1,55

—0,07

All Around

Example
Solder Mask Opening
(See Note E)

4211283−2/E 08/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		